

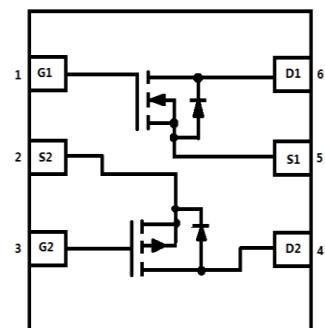
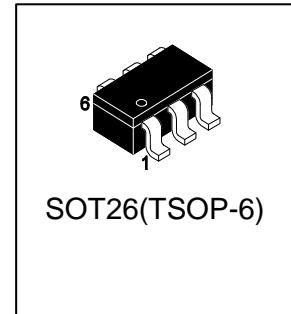
LNP2601T1G

S-LNP2601T1G

20 V Complementary Trench MOSFET

1. FEATURES

- N-Channel: VDS = 20V
RDS(ON) ≤ 60mΩ, VGS@4.5V, IDS@1A
RDS(ON) ≤ 75mΩ, VGS@2.5V, IDS@1A
RDS(ON) ≤ 100mΩ, VGS@1.8V, IDS@1A
- P-Channel: VDS = -20V
RDS(ON) ≤ 80mΩ, VGS@-4.5V, IDS@-1.0A
RDS(ON) ≤ 95mΩ, VGS@-2.5V, IDS@-1.0A
RDS(ON) ≤ 120mΩ, VGS@-1.8V, IDS@-1.0A
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LNP2601T1G	NP1	3000/Tape&Reel

3. Absolute Maximum Ratings (TA = 25 °C unless otherwise noted)

Parameter (N-Channel)	Symbol	Limits	Unit
Drain-Source Voltage	VDS	20	V
Gate-Source Voltage	VGS	± 8	V
Drain Current-Continuous	ID	3	A
Drain Current-Pulsed	IDM	11	A
Operating Junction and Storage Temperature Range	TJ ,TSTG	-55 ~ +150	°C

Parameter (P-Channel)	Symbol	Limits	Unit
Drain-Source Voltage	VDS	-20	V
Gate-Source Voltage	VGS	± 8	V
Drain Current-Continuous	ID	-2.5	A
Drain Current-Pulsed	IDM	-9	A
Operating Junction and Storage Temperature Range	TJ ,TSTG	-55 ~ +150	°C

1. Repetitive Rating: Pulse width limited by the maximum junction temperature

2. 1-in² 2oz Cu PCB board

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

N-Channel

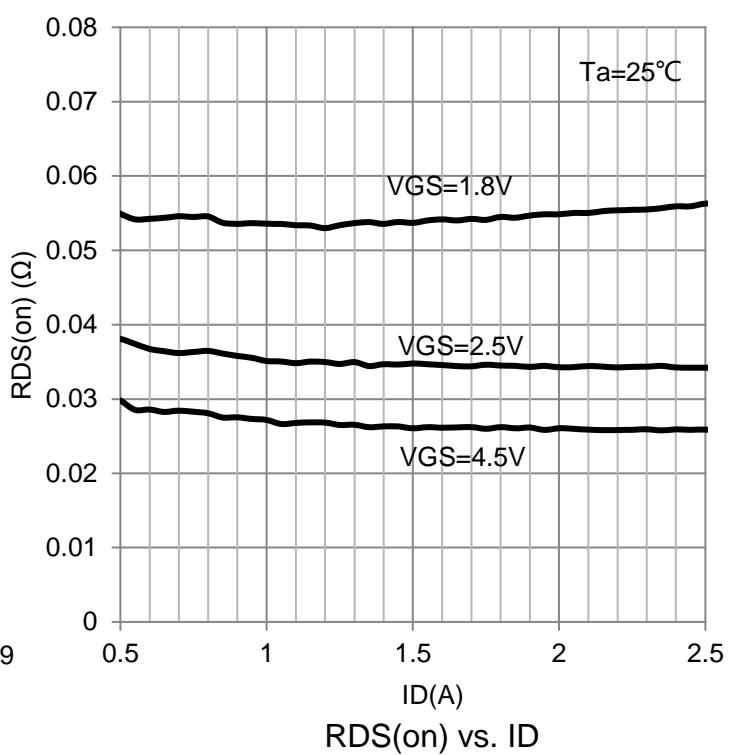
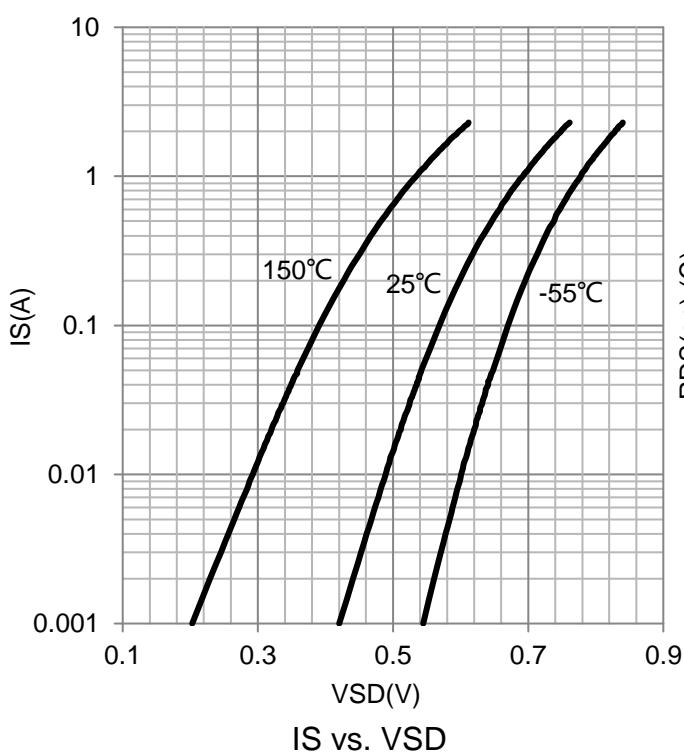
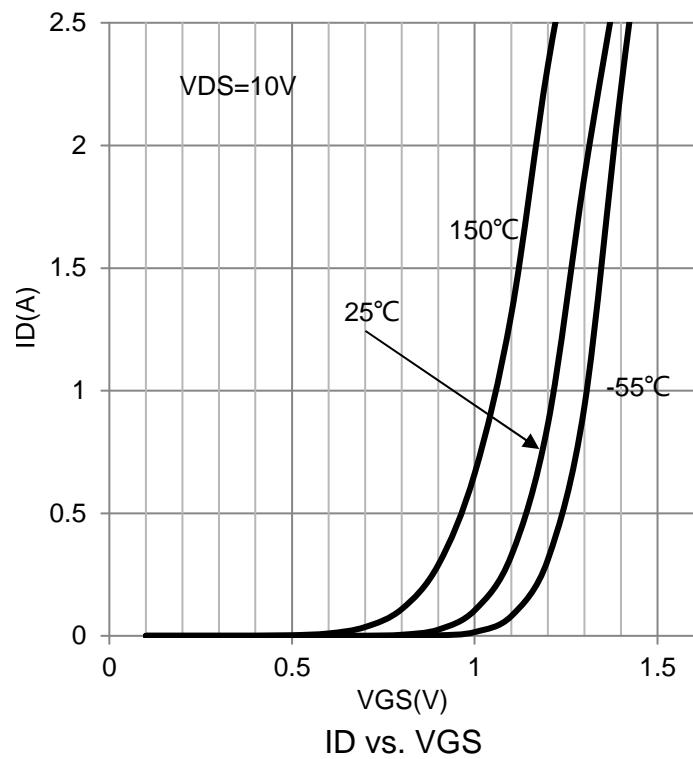
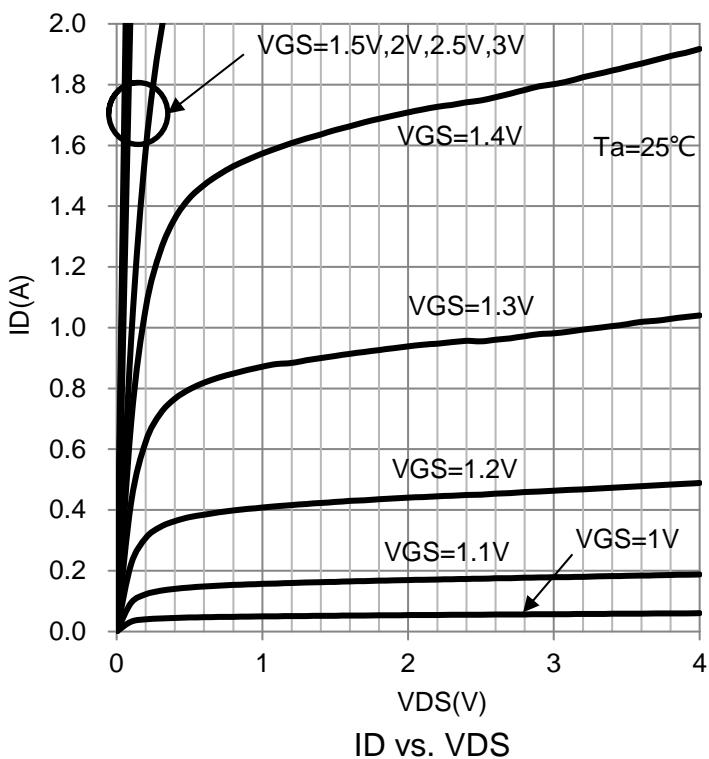
Parameter	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage (VGS =0V ID =250μA)	BVDSS	20	-	-	V
Drain-Source On-State Resistance (VGS=4.5V, ID=1.0A) (VGS=2.5V, ID=1.0A) (VGS=1.8V, ID=1A)	RDS(on)	-	-	60	mΩ
		-	-	75	
		-	-	100	
Gate Threshold Voltage (VDS = VGS, ID =250uA)	VGS(th)	0.4	-	1.2	V
Zero Gate Voltage Drain Current (VDS = 20V, VGS = 0V)	IDSS	-	-	1.0	uA
Gate Body Leakage (VGS =± 8V, VDS = 0V)	IGSS	-	-	±1	uA
Source-Drain Diode					
Diode Forward Voltage (IS = 1.0A, VGS = 0V)	VSD	-	-	1.5	V
Dynamic					
Input Capacitance	(VDS =8V, VGS = 0V, f=1MHz)	Ciss	642		pF
Output Capacitance		Coss	62.4		
Reverse Transfer Capacitance		Crss	53.6		
Total Gate Charge	(VDS =10V, ID=6A, VGS=4.5V)	Qg	6.7		nC
Gate-Source Charge		Qgs	0.87		
Gate-Drain Charge		Qgd	2.34		
Turn-On Delay Time	(VDD=10V,RG =6.2Ω, ID = 1A, VGS= 4.5V,RL= 10Ω, tp=10us)	td(on)	11.5		ns
Turn-On Rise Time		tr	16		
Turn-Off Delay Time		td(off)	72.7		
Turn-Off Fall Time		tf	24.6		
Gate Resistance (VDS=0V,VGS=0V,f=1.0MHz)	Rg	-	5.25	-	Ω

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

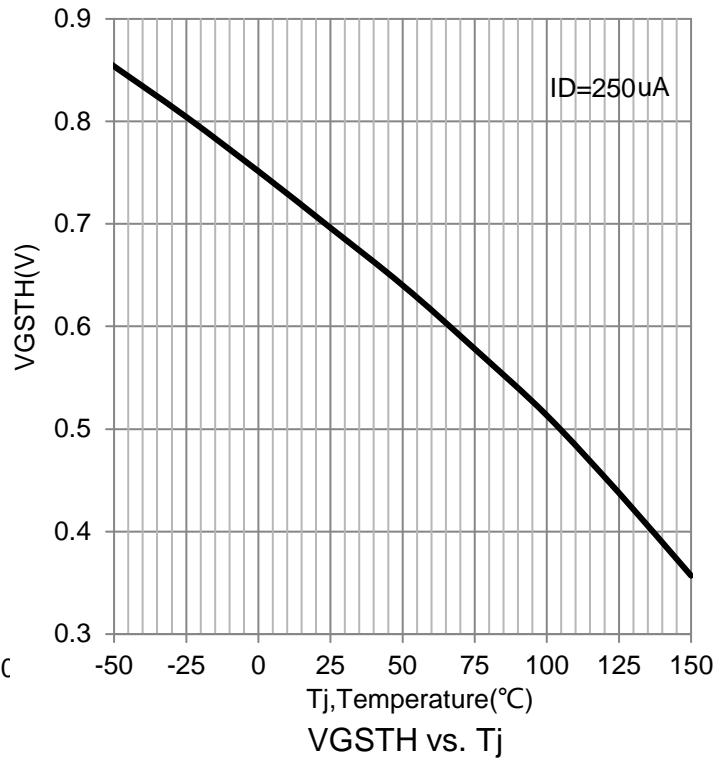
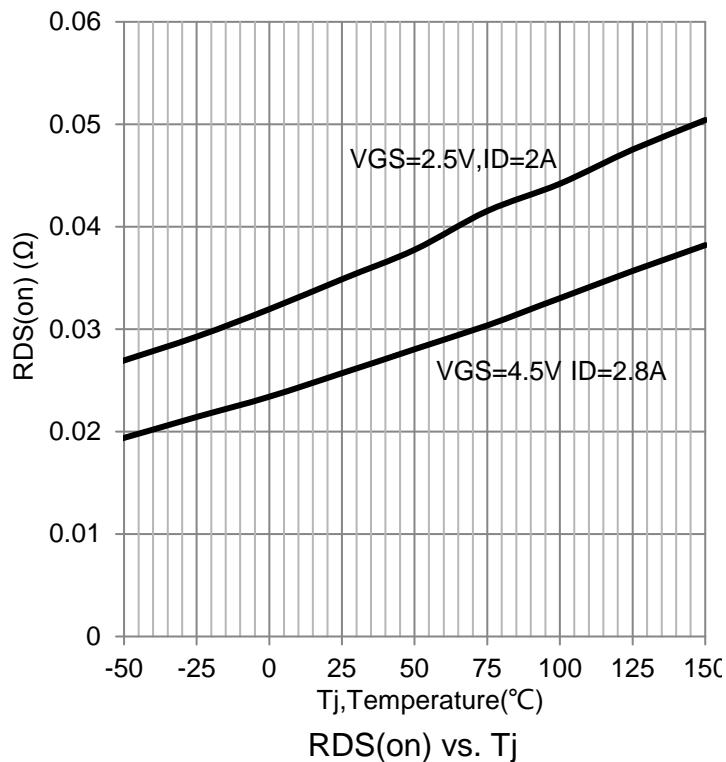
P-Channel

Parameter	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage (VGS =0V ID =-250μA)	BVDSS	-20	-	-	V
Drain-Source On-State Resistance (VGS=-4.5V, ID=-1.0A) (VGS=-2.5V, ID=-1.0A) (VGS=-1.8V, ID=-1.0A)	RDS(on)	-	-	80	mΩ
		-	-	95	
		-	-	120	
Gate Threshold Voltage (VDS = VGS, ID =-250uA)	VGS(th)	-0.4	-	-1	V
Zero Gate Voltage Drain Current (VDS = -20V, VGS = 0V)	IDSS	-	-	-1	uA
Gate Body Leakage (VGS =± 8V, VDS = 0V)	IGSS	-	-	±1	uA
Source-Drain Diode					
Diode Forward Voltage (IS = -1.0A, VGS = 0V)	VSD	-	-	-1.5	V
Dynamic					
Input Capacitance	(VDS = -4V, VGS = 0V, f=1MHz)	Ciss		667	pF
Output Capacitance		Coss		85	
Reverse Transfer Capacitance		Crss		70.5	
Total Gate Charge	(VDS =-6V, ID=-2.8A, VGS=-4.5V)	Qg		9.1	nC
Gate-Source Charge		Qgs		2.0	
Gate-Drain Charge		Qgd		1.7	
Turn-On Delay Time	(VDD=-4V,RL =4.1Ω, ID = -1A, VGEN= -4.5V, RG= 6.2Ω)	td(on)		11.6	ns
Turn-On Rise Time		tr		14.7	
Turn-Off Delay Time		td(off)		62.4	
Turn-Off Fall Time		tf		23.6	
Gate Resistance (VDS=0V,VGS=0V,f=1.0MHz)	Rg	-	4.8	-	Ω

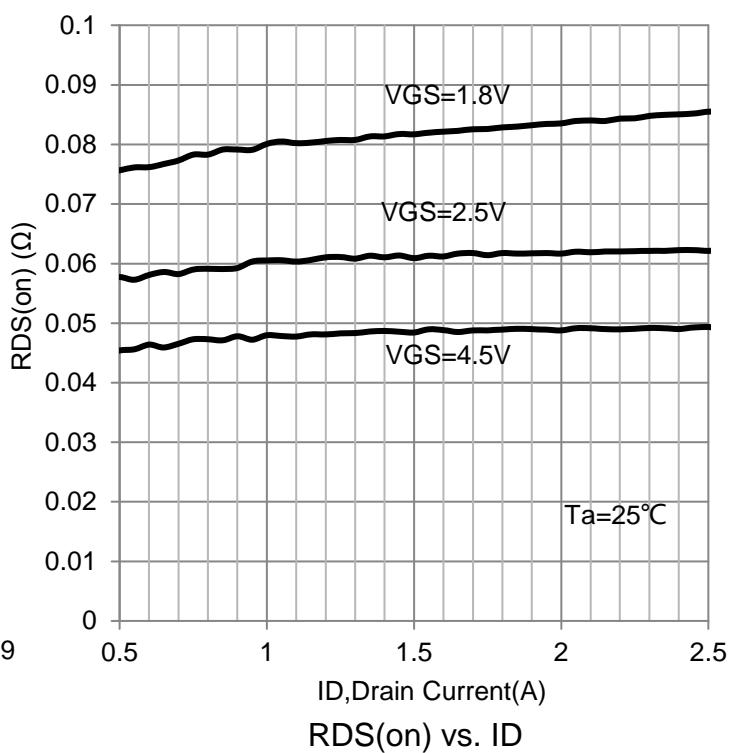
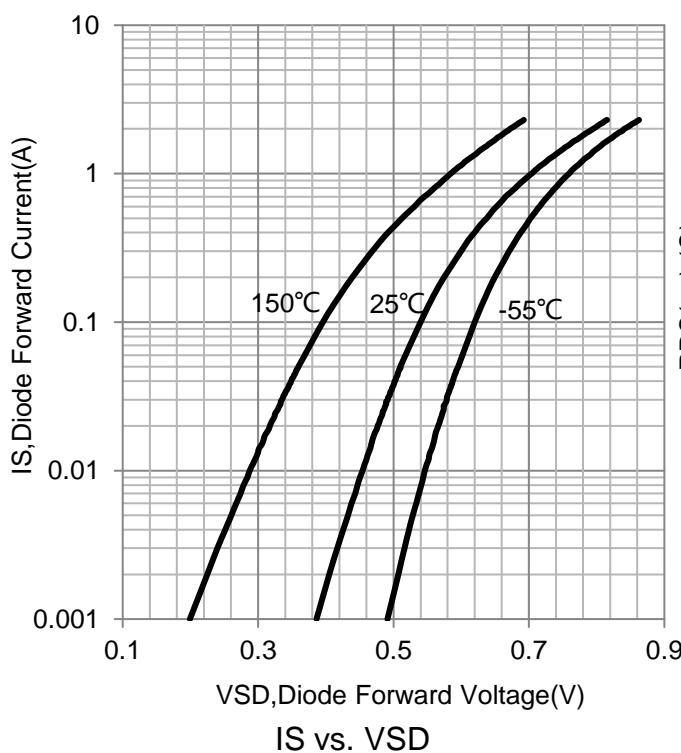
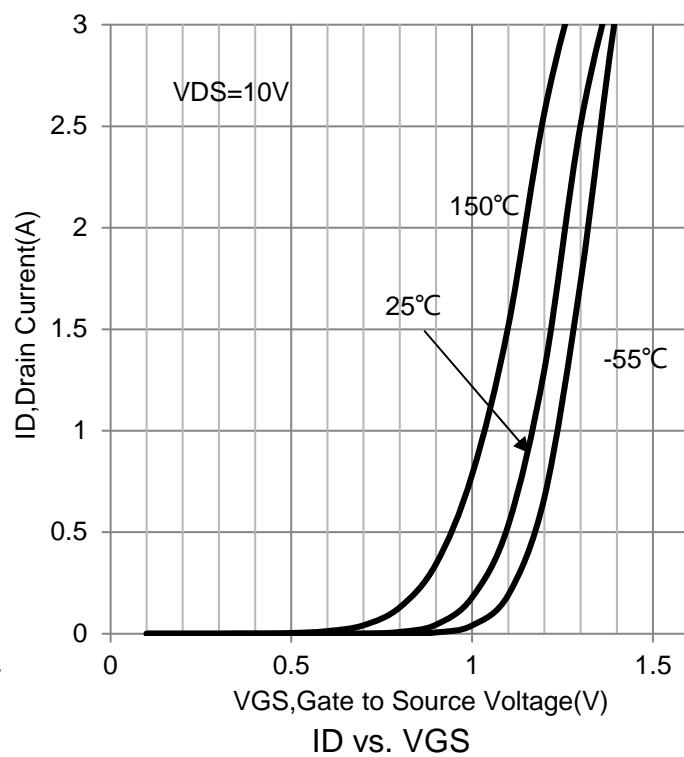
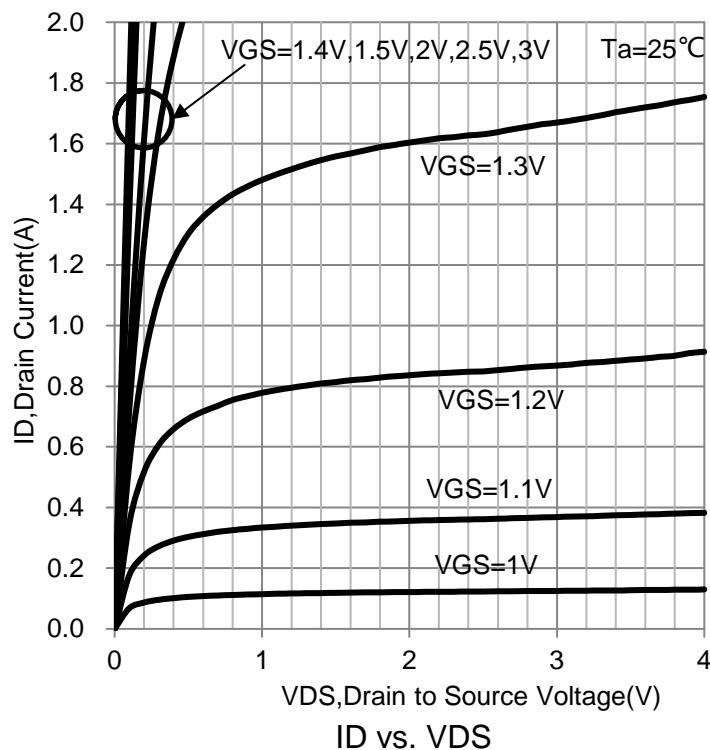
5.ELECTRICAL CHARACTERISTICS CURVES(N-Channel)



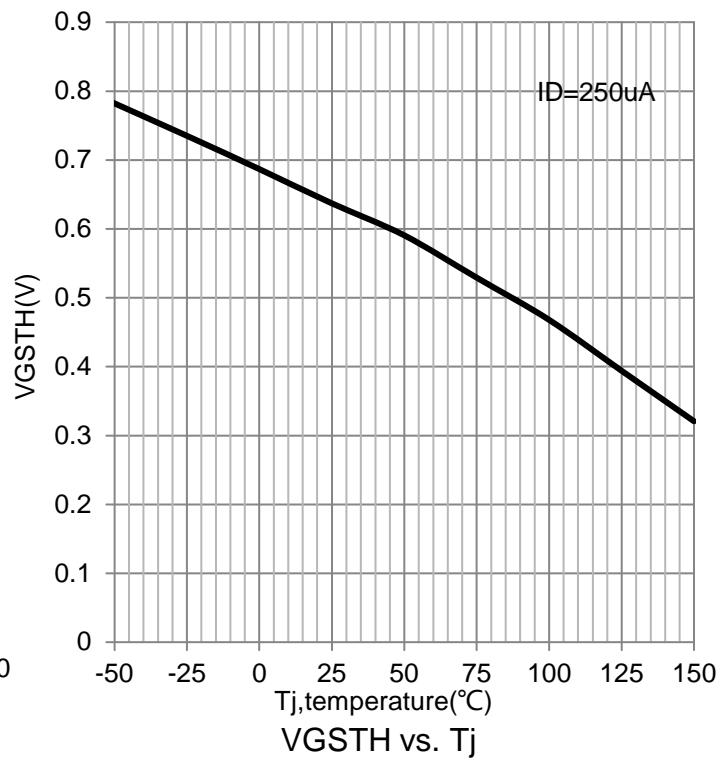
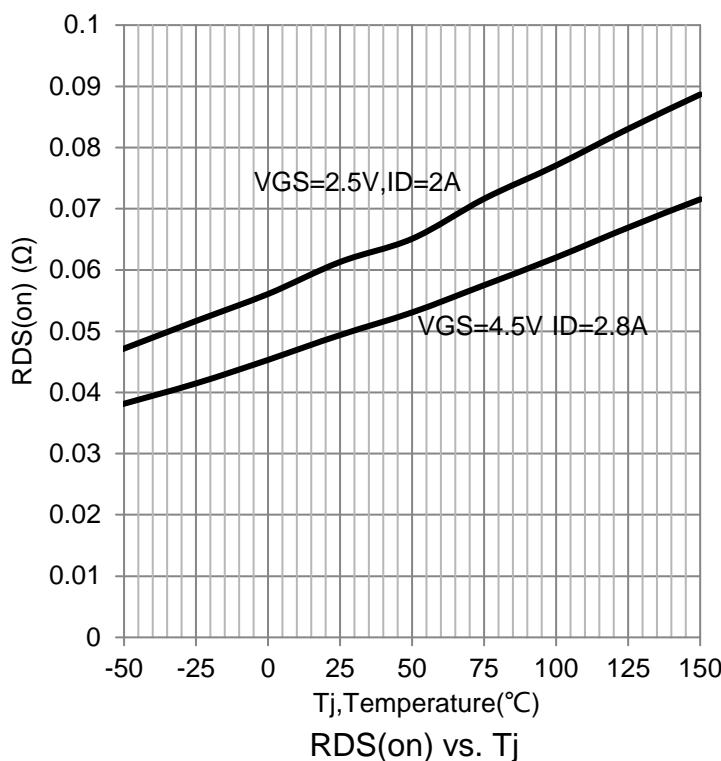
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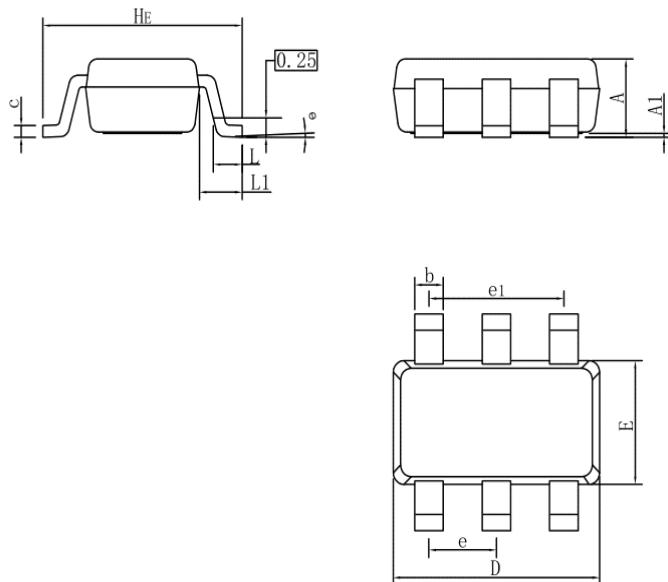
5.ELECTRICAL CHARACTERISTICS CURVES(P-Channel)



5.ELECTRICAL CHARACTERISTICS CURVES(P-Channel)(Con.)

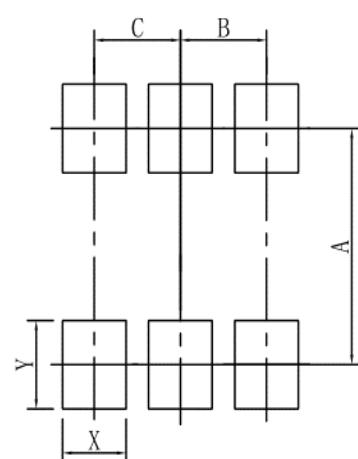


6.OUTLINE AND DIMENSIONS



SOT26			
DIM	MIN	NOR	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
c	0.10	0.17	0.20
D	2.80	2.90	3.00
E	1.50	1.60	1.70
e	0.85	0.95	1.05
e1	1.80	1.90	2.00
L	0.20	0.40	0.60
L1	0.60REF		
HE	2.60	2.80	3.00
θ	0 °	-	10 °

7.SOLDERING FOOTPRINT



SOT26	
DIM	(mm)
X	0.70
Y	0.90
A	2.40
B	0.95
C	0.95